METHOD AND SYSTEM FOR REMOVING TAPE FROM SUBSTRATES

ABSTRACT

A method for removing tape from a substrate includes the step of detecting an actual distance between a peel head and the tape on the substrate, and a location of an edge of the substrate. The method also includes the steps of moving the peel head in a first direction by an amount equal to the distance to press the peel tape onto the tape on the substrate, moving the peel head in a second direction to the edge of the substrate, and then moving the peel head in an opposite second direction to peel the tape from the substrate. The detecting step can be performed using a sensor such as a capacitance probe sensor or an optical sensor. Alternately, rather than detecting the distance, a pressure sensing system can be used to press the peel head against the tape, and to maintain a predetermined pressure range during the peeling process. A system for performing the method includes sensors configured to detect the distance and the edge of the substrate, and a control system configured to control the movement of the peel head responsive to signals from the sensors. A pressure sensing system includes a compression spring and a load cell for sensing pressure, and a stepper motor configured to control movement of the peel head responsive to pressure signals.